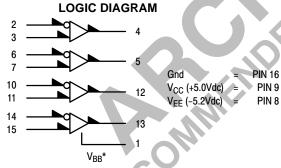
# **Quad MECL to TTL Translator**

The MC10125 is a quad translator for interfacing data and control signals between the MECL section and saturated logic sections of digital systems. The MC10125 incorporates differential inputs and Schottky TTL "totem pole" outputs. Differential inputs allow for use as an inverting/ non-inverting translator or as a differential line receiver. The V<sub>BB</sub> reference voltage is available on pin 1 for use in single-ended input biasing. The outputs of the MC10125 go to a low logic level whenever the inputs are left floating.

Power supply requirements are ground, +5.0 Volts and -5.2 Volts. Propagation delay of the MC10125 is typically 4.5 ns. The MC10125 has fanout of 10 TTL loads. The dc levels are MECL 10,000 in and Schottky TTL, or TTL out. This device has an input common mode noise rejection of  $\pm$  1.0 Volt.

An advantage of this device is that MECL level information can be received, via balanced twisted pair lines, in the TTL equipment. This isolates the MECL logic from the noisy TTL environment. This device is useful in computers, instrumentation, peripheral controllers, test equipment and digital communications systems.

- $P_D = 380 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 4.5 \text{ ns typ } (50\% \text{ to} + 1.5 \text{ Vdc out})$
- $t_r$ ,  $t_f = 2.5$  ns typ (1.0 V to 2.0 V)



\*V<sub>BB</sub> to be used to supply bias to the MC10125 only and bypassed (when used) with 0.01  $\mu$ F to 0.1  $\mu$ F capacitor to ground (0 V). V<sub>BB</sub> can source < 1.0 mA.

When the input pin with the bubble goes positive, the output goes negative.

#### **DIP PIN ASSIGNMENT** 16 **GND** 15 $D_{IN}$ A<sub>IN</sub> $\overline{\mathsf{D}_{\mathsf{IN}}}$ 14 13 D<sub>OUT</sub> $B_{\text{OUT}}$ 5 12 COUT $C_{\text{IN}}$ B<sub>IN</sub> 6 11 $\mathsf{B}_{\mathsf{IN}}$ 7 10 CIN 9 $V_{EE}$ $V_{CC}$

Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



## ON Semiconductor

http://onsemi.com

#### **MARKING DIAGRAMS**



CDIP-16 **L SUFFIX CASE 620** 





PDIP-16 P SUFFIX **CASE 648** 





PLCC-20 **FN SUFFIX CASE 775** 



= Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

#### ORDERING INFORMATION

Device	Package	Shipping
MC10125L	CDIP-16	25 Units / Rail
MC10125P	PDIP-16	25 Units / Rail
MC10125FN	PLCC-20	46 Units / Rail

#### **ELECTRICAL CHARACTERISTICS**

-11	Pin		100	Test Limits			-00		
	Under	-30		NA:	+25°C	Marr	+85	1	
nbol	Test 8	Min	<b>Max</b> -44	Min	Тур	Max	Min	<b>Max</b> -44	Uni
E	8		<del>-44</del>			-40		<del>-44</del>	mAd
СН	9		52			52		52	mAd
CL	9		39			39		39	mAc
nH <sup>1</sup>	2		180			115		115	μAd
ВО	2		1.5			1.0		1.0	μAd
ОН	4	2.5		2.5			2.5		Vdd
OL	4		0.5			0.5		0.5	Vdd
OHA	4	2.5		2.5			2.5	C	Vdd
DLA	4		0.5			0.5		0.5	Vdd
LS1	4		0.5			0.5		0.5	Vdd
LS2	4		0.5			0.5		0.5	Vdo
os	4	40	100	40		100	40	100	mAc
ВВ	1	-1.420	-1.280	-1.350		-1.230	-1.295	-1.150	Vdd
ОН	4 4	2.5 2.5		2.5 2.5			2.5 2.5		Vdd
OL	4 4		0.5 0.5		0	0.5 0.5		0.5 0.5	Vdd
		•			O				ns
+5- -5+ +4-	5 5 4	1.0 1.0 1.0	6.0 6.0 6.0	1.0 1.0 1.0	4.5 4.5 4.5	6.0 6.0 6.0	1.0 1.0 1.0	6.0 6.0 6.0	
-4+ 4+	4		3.3	1.0	4.0	3.3	1.0	3.3	
4-	4		3.3			3.3		3.3	
	H1 BO DH DL DHA DLA LS1 LS2 DS BB DH DL S5-4-4-4+ LF	H <sup>1</sup> 2 BO 2 DH 4 DL 4 DHA 4 DHA 4 DLA 4 LS1 4 LS2 4 DS 4 DS 4 DH	H1 2 BO 2 DH 4 2.5 DL 4 DHA 4 2.5 DL 4 DHA 4 2.5 DLA 4 LS1 4 LS2 4 DS 4 40 DH 4 2.5 DH 4 2.5 DH 4 2.5 DH 4 1.0	H <sup>1</sup> 2 180 BO 2 1.5 DH 4 2.5 DH 4 2.5 DL 4 0.5 DHA 4 0.5 DLA 4 0.5 LS1 4 0.5 LS2 4 0.5 DB 4 40 100 DB 1 -1.420 -1.280 DH 4 2.5 DL 4 2.5 DL 4 0.5 DL	H <sup>1</sup> 2 180 BO 2 1.5 DH 4 2.5 2.5 DL 4 0.5 DHA 4 2.5 2.5 DLA 4 0.5 DLA 4 0.5 DLS1 4 0.5 DLS2 4 0.5 DS 4 40 100 40 DS 4 40 100 40 DS 4 2.5 2.5 DH 4 2.5 2.5 DH 4 2.5 2.5 DL 4 0.5 DH 4 2.5 2.5 DL 4 0.5 DH 4 2.5 2.5 DL 4 0.5 DL 0.	H <sup>1</sup> 2 180 BO 2 1.5 DH 4 2.5 2.5 DL 4 0.5 DLA 4 0.5 DLA 4 0.5 DLA 4 0.5 DLS1 4 0.5 DLS2 4 0.5 DL 4 0.5	H <sup>1</sup> 2 180 115 1.0 1.0 1.0 1.0 1.0 1.0 1.0 1.0 1.0 1.0	H <sup>1</sup> 2 180 115 10 10 115 10 10 115 10 10 10 10 10 10 10 10 10 10 10 10 10	H <sup>1</sup> 2 180 115 115 116 10 10 10 10 10 10 10 10 10 10 10 10 10

Individually test each output, apply V<sub>IHmax</sub> to pin under test.

#### **ELECTRICAL CHARACTERISTICS** (continued)

			TEST VOLTAGE VALUES (Volts)							
	@ Test Temp	perature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>IHH</sub>	V <sub>ILH</sub>		
		–30°C	-0.890	-1.890	-1.205	-1.500	+0.110	-0.890		
		+25°C	-0.810	-1.850	-1.105	-1.475	+0.190	-0.850		
		+85°C	-0.700	-1.825	-1.035	-1.440	+0.300	-0.825		
		Pin	TEST	VOLTAGE A	APPLIED TO	PINS LIST	ED BELC	W		•
Characteristic	Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>IHH</sub>	V <sub>ILH</sub>	Gnd	Output Condition
Negative Power Supply Drain Current	lΕ	8							16	
Positive Power Supply	I <sub>CCH</sub>	9	2,6,10,14						16	
Drain Current	I <sub>CCL</sub>	9		2,6,10,14					16	
Input Current	I <sub>inH</sub> 1	2	2,6,10,14						16	
Input Leakage Current	I <sub>CBO</sub>	2							16	
High Output Voltage	V <sub>OH</sub>	4		2,6,10,14					16	–2.0mA
Low Output Voltage	V <sub>OL</sub>	4	2,6,10,14						16	20mA
High Threshold Voltage	V <sub>OHA</sub>	4		6,10,14		2			16	–2.0mA
Low Threshold Voltage	V <sub>OLA</sub>	4	6,10,14		2				16	20mA
Indeterminate Input	V <sub>OLS1</sub>	4							16	20mA
Protection Tests	V <sub>OLS2</sub>	4							16	20mA
Short Circuit Current	Ios	4		2,6,10,14		70			4, 16	
Reference Voltage	$V_{BB}$	1		2,6,10,14						
Common Mode Rejection Tests	V <sub>OH</sub>	4 4					3	2	16 16	−2.0mA −2.0mA
	V <sub>OL</sub>	4 4					2	3	16 16	20mA 20mA
Switching Times (50Ω Load)			Pulse In	Pulse Out	C <sub>L</sub> (pF)					
Propagation Delay (50% to +1.5Vdc)	t <sub>6+5-</sub> t <sub>6-5+</sub> t <sub>2+4-</sub> t <sub>2-4+</sub>	5 5 4 4	6 6 2 2	5 5 4 4	25 25 25 25				16 16 16 16	
Rise Time(+1.0V to 2.0V)	t <sub>4+</sub>	4	2	4	25				16	
Fall Time (+1.0V to 2.0V)	t <sub>4-</sub>	4	2	4	25				16	

<sup>1.</sup> Individually test each output, apply V<sub>IHmax</sub> to pin under test.

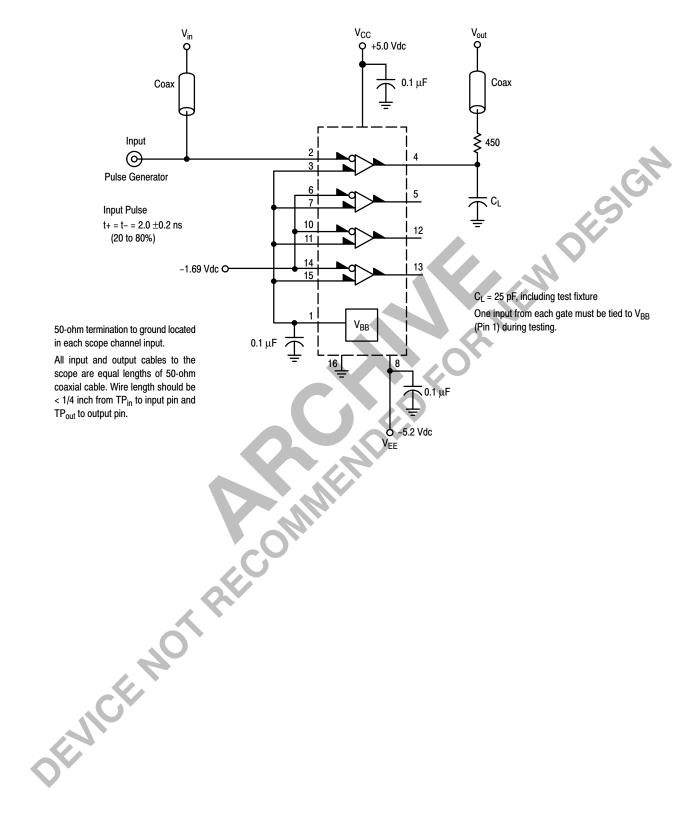
## **ELECTRICAL CHARACTERISTICS** (continued)

			TEST VOLTAGE VALUES (Volts)						
@ Test Temperature			V <sub>IHH</sub>	V <sub>ILH</sub>	V <sub>BB</sub>	V <sub>CC</sub>	V <sub>EE</sub>		
		-30°C	-1.890	-2.890	From	+5.0	-5.2		
+25°C		-1.810	-2.850	Pin	+5.0	-5.2			
	+85°C				1	+5.0	-5.2		
		Pin Under	TEST	VOLTAG	E APPLIED TO	PINS LISTE	D BELOW		Outmut
Characteristic	Symbol	Test	V <sub>IHH</sub>	V <sub>ILH</sub>	V <sub>BB</sub>	V <sub>CC</sub>	V <sub>EE</sub>	Gnd	Output Condition
Negative Power Supply Drain Current	ΙE	8			3,7,11,15	9	8	16	
Positive Power Supply	I <sub>CCH</sub>	9			3,7,11,15	9	8	16	
Drain Current	I <sub>CCL</sub>	9			3,7,11,15	9	8	16	1
Input Current	I <sub>inH</sub> 1	2			3,7,11,15	9	8	16	
Input Leakage Current	I <sub>CBO</sub>	2			3,7,11,15	9	2,6,8,10,14	16	)
High Output Voltage	V <sub>OH</sub>	4			3,7,11,15	9	8	16	-2.0mA
Low Output Voltage	V <sub>OL</sub>	4			3,7,11,15	9	8	16	20mA
High Threshold Voltage	V <sub>OHA</sub>	4			3,7,11,15	9	8	16	-2.0mA
Low Threshold Voltage	V <sub>OLA</sub>	4			3,7,11,15	9	8	16	20mA
Indeterminate Input Protection Tests	V <sub>OLS1</sub>	4				9	2,3,6,7,8, 10,11,14,15	16	20mA
	V <sub>OLS2</sub>	4				9	8	16	20mA
Short Circuit Current	Ios	4			3,7,11,15	9	8	4, 16	
Reference Voltage	$V_{BB}$	1			3,7,11,15				
Common Mode Rejection Tests	V <sub>OH</sub>	4 4	3	2		9 9	8 8	16 16	–2.0mA –2.0mA
	V <sub>OL</sub>	4	2	3		9	8 8	16 16	20mA 20mA
Switching Times (50Ω Load)				71					
Propagation Delay (50% to +1.5Vdc)	$t_{6+5-}$ $t_{6-5+}$ $t_{2+4-}$ $t_{2-4+}$	5 5 4 4	RIL		3,7,11,15 3,7,11,15 3,7,11,15 3,7,11,15	9 9 9	8 8 8	16 16 16 16	
Rise Time (+1.0V to 2.0V)	t <sub>4+</sub>	4			3,7,11,15	9	8	16	
Fall Time (+1.0V to 2.0V)	t <sub>4-</sub>	4			3,7,11,15	9	8	16	

Individually test each output, apply V<sub>IHmax</sub> to pin under test.

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibitum has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

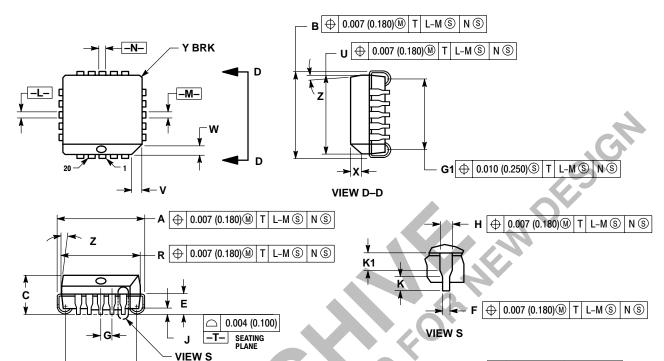
#### **SWITCHING TIME TEST CIRCUIT**



#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

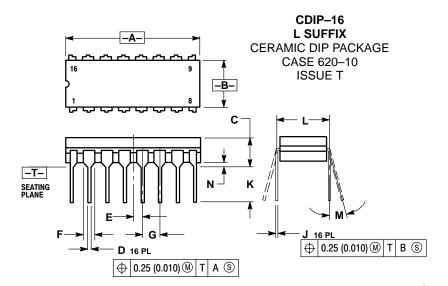
  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	0.050 BSC 1.27		BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

#### PACKAGE DIMENSIONS



#### NOTES:

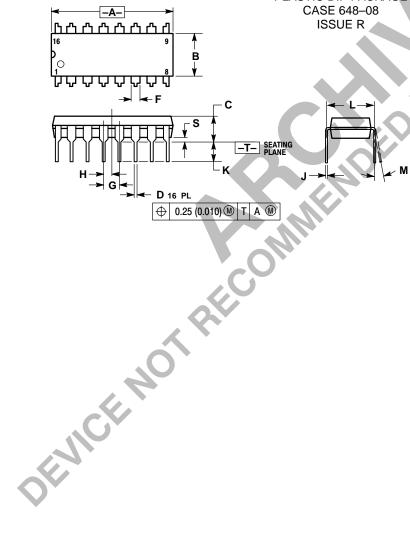
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	



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